Form PTO-1449 (modified)
List of Patents and Publications
For Applicant's Information
Disclosure Statement
(Use several sheets if necessary)

EXAMINER:

ATTY. DOCKET NO: 5298-05500

SERIAL NO: 09/476,669



APPLICANT: Lau

FILING DATE: December 30, 1999

GROUP: 2811

U.S. PATENT DOCUMENTS							
REF. DES	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE	
AA	4,970,176	11/13/90	Tracy et al.				
AB	5,108,570	4/28/92	Wang				
AC	5,108,951	4/28/92	Chen et al.				
AD	5,270,255	12/14/93	Wong				
AE	5,288,665	2/22/94	Nulman				
AF	5,358,616	10/25/94	Ward		<u>-</u> ,		
AG	5,371,042	12/6/94	Ong				
AH	5,378,660	1/3/95	Ngan et al.				
ΑI	5,443,995	8/22/95	Nulman				
AJ	5,600,182	2/4/97	Schinella et al.	R	CLIV	こり	
AK	5,665,659	9/9/97	Lee et al.	MAY	2 5 2fini		
AL	5,693,564	12/2/97	Yu				
AM	5,731,245	3/24/98	Joshi et al.	TECHNOLOG	Y CENTER 20)U	
	DES AA AB AC AD AE AF AG AH AI AI AJ AK AL	REF. DOCUMENT NUMBER AA 4,970,176 AB 5,108,570 AC 5,108,951 AD 5,270,255 AE 5,288,665 AF 5,358,616 AG 5,371,042 AH 5,378,660 AI 5,443,995 AJ 5,600,182 AK 5,665,659 AL 5,693,564	REF. DOCUMENT NUMBER AA 4,970,176 11/13/90 AB 5,108,570 4/28/92 AC 5,108,951 4/28/92 AD 5,270,255 12/14/93 AE 5,288,665 2/22/94 AF 5,358,616 10/25/94 AG 5,371,042 12/6/94 AH 5,378,660 1/3/95 AI 5,443,995 8/22/95 AJ 5,600,182 2/4/97 AK 5,665,659 9/9/97 AL 5,693,564 12/2/97	REF. DOCUMENT NUMBER DATE NAME AA 4,970,176 11/13/90 Tracy et al. AB 5,108,570 4/28/92 Wang AC 5,108,951 4/28/92 Chen et al. AD 5,270,255 12/14/93 Wong AE 5,288,665 2/22/94 Nulman AF 5,358,616 10/25/94 Ward AG 5,371,042 12/6/94 Ong AH 5,378,660 1/3/95 Ngan et al. AI 5,443,995 8/22/95 Nulman AJ 5,600,182 2/4/97 Schinella et al. AK 5,665,659 9/9/97 Lee et al. AL 5,693,564 12/2/97 Yu	REF. DES DOCUMENT NUMBER DATE NAME CLASS AA 4,970,176 11/13/90 Tracy et al. Image: Common state of the common s	REF. DOCUMENT NUMBER DATE NAME CLASS SUB CLASS AA 4,970,176 11/13/90 Tracy et al. Tracy et al. AB 5,108,570 4/28/92 Wang Wang AC 5,108,951 4/28/92 Chen et al. AD 5,270,255 12/14/93 Wong AE 5,288,665 2/22/94 Nulman AF 5,358,616 10/25/94 Ward AG 5,371,042 12/6/94 Ong AH 5,378,660 1/3/95 Ngan et al. AI 5,443,995 8/22/95 Nulman AJ 5,600,182 2/4/97 Schinella et al. RICCASS AK 5,665,659 9/9/97 Lee et al. MAY 2.5 2fintt AL 5,693,564 12/2/97 Yu ACCASS	

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)					
Иc	AN	Xu et al., "Plar Multilevel Metallization Technologies for ULSI Devices," SPIE Vol. 2335, 1994, pp. 70-79.			
ガC	AO	Xu et al., "A1 planarization processes for multilayer metallization of quarter micrometer devices," Thin Solid Films, Vol. 253, 1994, pp. 367-371.			
AC.	AP	Singer, "The Interconnect Challenge: Filling Small, High Aspect Ratio Contact Holes," Semiconductor International, August 1994, 5 pages.			
B C	AQ	Robinson, "A1 hits sub-0.25 micron vias," pp. 37 and 42, Electronic Engineering Times, Issue 339, February 1997.			
AC.	AR	Metal Deposition Products, Applied Materials-Products and Services, 5 pages, printed November 1999, © 1999 Applied Materials, Inc.			
A C	AS	"Ionized Physical Vapor Deposition," printed December 1999, www.ece.neu.edu/edsnu/hopwood, 8 pages.			

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the patent owner.

DATE CONSIDERED: